3.60±0.05

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Open Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 250°C/10 seconds at terminals

Mechanical Data

Case: JEDEC 60B molded plastic body

Terminals: Solderable per MIL-STD-750, Method 2026 Polarity: Polarity symbol marking on body Mounting

Position: Any

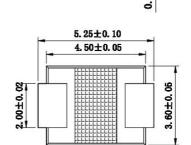
Weight: 0.005ounce, 0.138grams

Maximum Ratings And Elect Characteristics

1.00±0. 1.90 ±0.2 1.30±0.2

DO-214AA/SMB

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Dimiensions in inches and (milimeters)

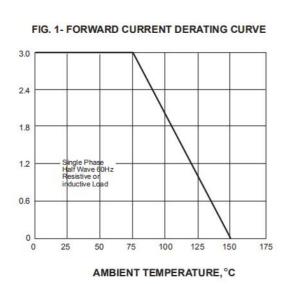
Ratings at 25 C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

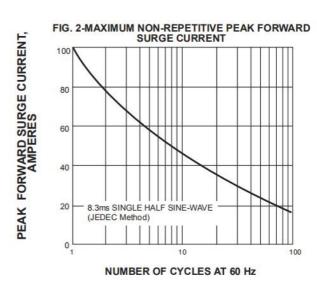
Type Number	SYMBOL	RS3M	uni t
Maximum Recurrent Peak Reverse Voltage	$V_{ m RRM}$	1000	V
Maximum RMS Voltage	$V_{ m RMS}$	700	V
Maximum DC blocking Voltage	V _{DC}	1000	V
Maximum Average Forward Rectified Current .at TA =55°C	$I_{\mathrm{F(AV)}}$	3	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{ m FSM}$	100.0	A
Maximum Forward Voltage at 2.0A DC	V_{F}	1.3	V
		5.0	
Maximum DC Reverse Current @T _A =25°C At rated DC blocking voltage @T _A =125°C	$I_{ m R}$	100	μΑ
Maximum reverse recovery time (Note1)	Trr	500	nS
Typical Junction Capacitance (Note2)	Cj	60	pF
Typical Thermal Resistance (Note 3)	$R_{ m (JA)}$	50	°C /W
Storage Temperature	T _{STG}	-55 to +150	°C
Operation Junction Temperature	$T_{ m J}$	-55 to +150	°C

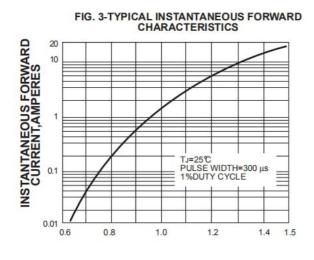
Note: 1. Reverse recovery condition IF=0.5A, IR=1.0A, Irr=0.25A 2.P.C.B. mounted with 2.0x2.0"(5x5cm) copper pad areas

3. The typical data above is for reference only.

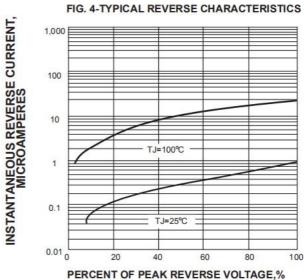
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES











INSTANTANEOUS FORWARD VOLTAGE, VOLTS

